



Tool Make & Model

Tool Configuration / Specifications



UltraTrimmer Plus™

**Wafer size
(mm)**

100,150,200

Process

Gas Cluster Beam

Performance

1 σ thickness variation <1nm

Applications

Etching(Frequency trimming, Thickness trimming),
Film Conversion(Oxidation, Nitridation),
Film smoothing ...etc.

Features

High throughput and low CoO,
Corrective etching (Location specific processing),
Room temperature process(No damage, Charging)

Browse our site at www.moov.co

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